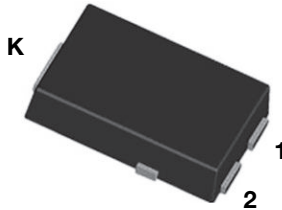
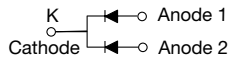


High Current Density Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier

 Ultra Low $V_F = 0.61\text{ V}$ at $I_F = 2\text{ A}$
eSMP[®] Series

SMPC (TO-277A)

LINKS TO ADDITIONAL RESOURCES

FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


**RoHS
COMPLIANT
HALOGEN
FREE**
TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters and polarity protection applications.

MECHANICAL DATA
Case: SMPC (TO-277A)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 4.0 A
V_{RRM}	200 V
I_{FSM}	80 A
V_F at $I_F = 4\text{ A}$	0.69 V
T_J max.	175 °C
Package	SMPC (TO-277A)
Circuit configuration	Common cathode

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V8P22C	UNIT
Device marking code		V822C	
Maximum repetitive peak reverse voltage	V_{RRM}	200	V
Maximum average forward rectified current per device (fig. 1)	$I_{F(AV)}$ ⁽¹⁾	8.0	A
	$I_{F(AV)}$ ⁽²⁾	3.1	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	80	A
Operating junction temperature range	T_J ⁽³⁾	-40 to +175	°C
Storage temperature range	T_J, T_{STG}	-55 to +175	°C

Notes

⁽¹⁾ Mounted on 30 mm x 30 mm pad areas aluminum PCB

⁽²⁾ Free air, mounted on recommended pad area

⁽³⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	$I_F = 2.0\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.76	-	V
	$I_F = 4.0\text{ A}$			0.83	0.90	
	$I_F = 2.0\text{ A}$	$T_J = 125\text{ }^\circ\text{C}$		0.61	-	
	$I_F = 4.0\text{ A}$			0.69	0.74	
Reverse current per diode	$V_R = 160\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.0002	-	mA
		$T_J = 125\text{ }^\circ\text{C}$		0.4	-	
	$V_R = 200\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$		-	0.08	
		$T_J = 125\text{ }^\circ\text{C}$		0.8	4	
Typical junction capacitance per diode	4.0 V, 1 MHz		C_J	165	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: Pulse width $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)			
PARAMETER	SYMBOL	V8P22C	UNIT
Typical thermal resistance per device	$R_{\theta JA}^{(1)(2)}$	85	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	5	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
(2) Free air, mounted on recommended copper pad area, 2 oz., FR4 PCB, thermal resistance $R_{\theta JA}$ - junction-to-ambient
(3) Units mounted on 30 mm x 30 mm aluminum PCB, thermal resistance $R_{\theta JM}$ - junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V8P22C-M3/H	0.10	H	1500	7" diameter plastic tape and reel
V8P22C-M3/I	0.10	I	6500	13" diameter plastic tape and reel
V8P22CHM3/H ⁽¹⁾	0.10	H	1500	7" diameter plastic tape and reel
V8P22CHM3/I ⁽¹⁾	0.10	I	6500	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

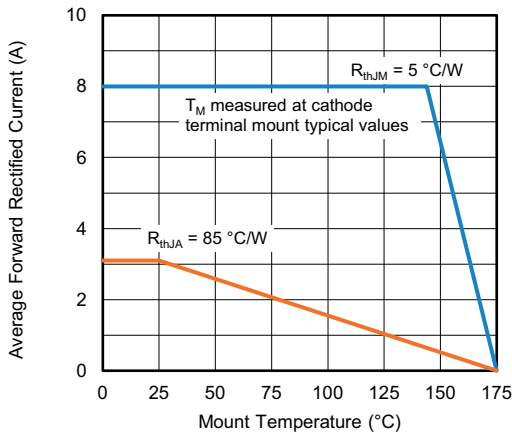


Fig. 1 - Maximum Forward Current Derating Curve

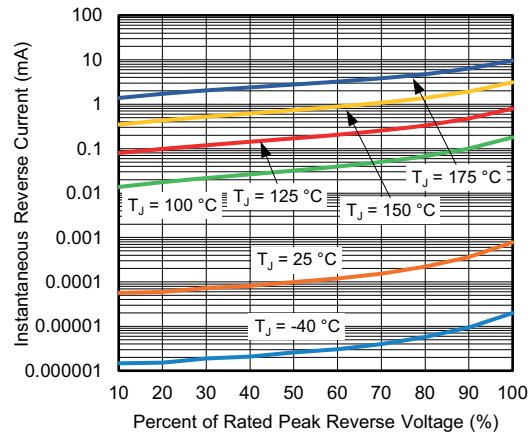


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

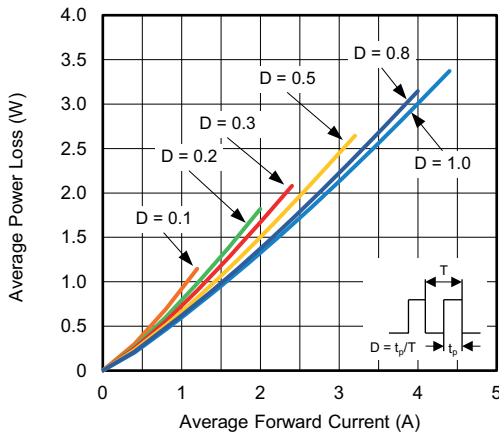


Fig. 2 - Forward Power Loss Characteristics Per Diode

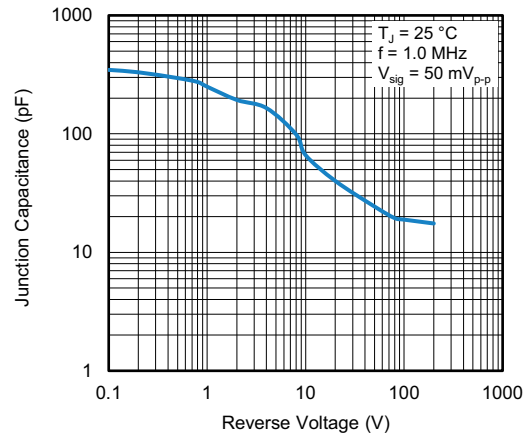


Fig. 5 - Typical Junction Capacitance Per Diode

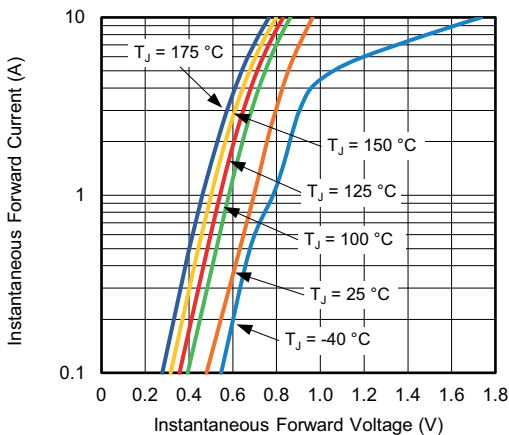


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

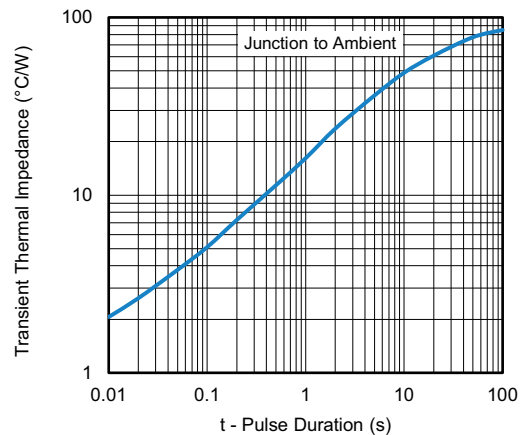
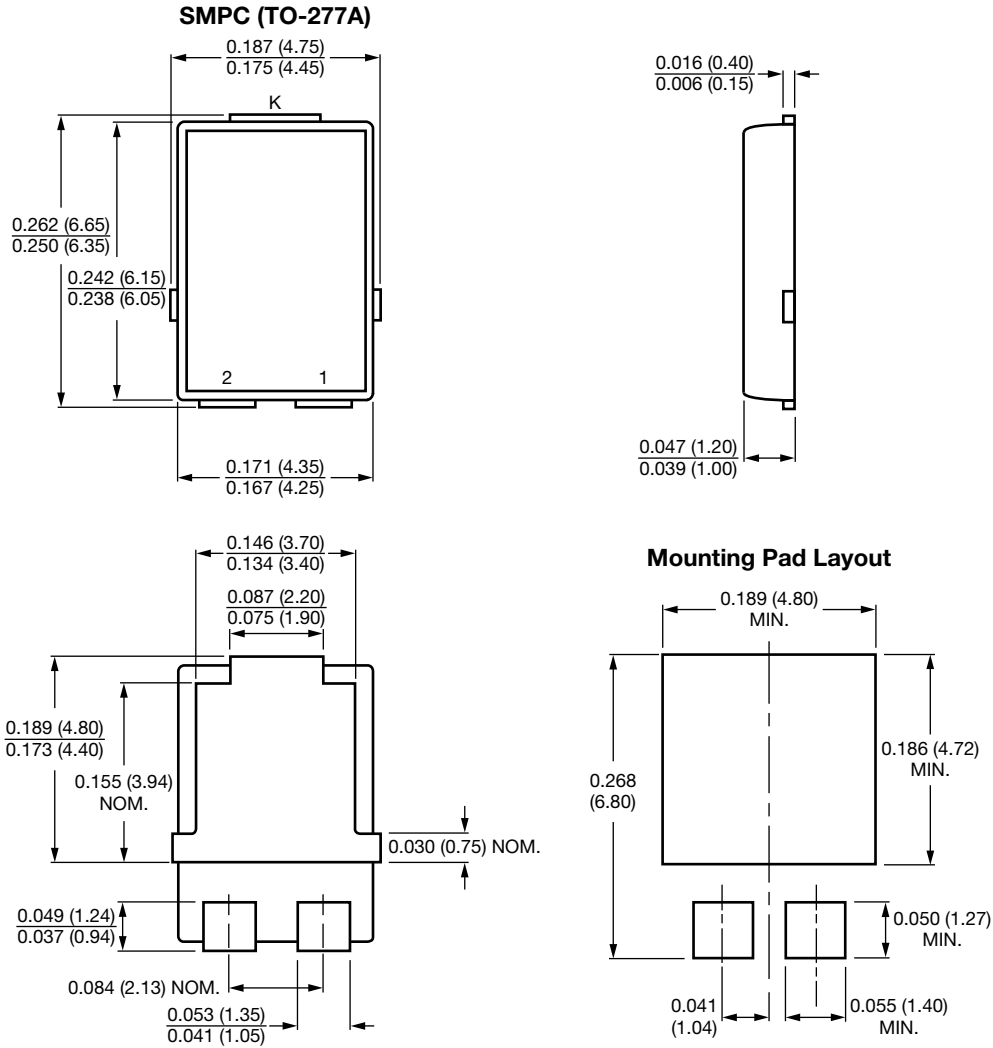


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



Conform to JEDEC® TO-277A



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